

Laird Connectivity

Wi-Fi Line Card



Laird Connectivity offers certified Wi-Fi modules that enable secure and reliable wireless connectivity, even in the harshest environments. Our modules are ideal for robust, business-critical connectivity in medical, industrial, and commercial settings where excellent RF performance, lower power consumption, simplified application development, and fast time to market are a must.

ENTERPRISE MODULES

- Designed for **Mission Critical** applications
- 'Always-On Connectivity' through advanced software
- Performance in harsh RF environments
- Multi-OS Support (Android/Linux)
- Enterprise Security
- Fast scanning & roaming
- Industry-leading Support & Extended Warranty

BETTER PERFORMANCE WITH THE SUMMIT STACK
CUSTOM FIRMWARE, CUSTOM SUPPLICANT, CONNECTION MANAGER, AND MUCH MORE.



PROFESSIONAL MODULES

- Designed for **Fast Time-to-Market**
- Broad Certifications
- Innovative Development Tools & Resources
- Industry-leading Design Support



60-SIPT

60-2230C

60 Series SOM

Sterling-LWB

Sterling-LWB5

TiWi-C-W

	60-SIPT	60-2230C	60 Series SOM	Sterling-LWB	Sterling-LWB5	TiWi-C-W
Chipset	Marvell 88W8997	Marvell 88W8997	Marvell 88W8997 Atmel ATSAMA5D36	Cypress CYW4343W	Cypress CYW43353	Cypress CYW4390
802.11 Standards	802.11 a/b/g/n/ac (2.4 and 5 GHz)	802.11 a/b/g/n/ac (2.4 and 5 GHz)	802.11 a/b/g/n/ac (2.4 and 5 GHz)	802.11 b/g/n (2.4 GHz)	802.11 ab/g/n/ac (2.4 GHz and 5 GHz)	802.11 b/g/n (2.4 GHz)
BT Standards	Dual-Mode Bluetooth v4.2	Dual-Mode Bluetooth v4.2	Dual-Mode Bluetooth v4.2	Classic Bluetooth and Dual-Mode BLE v4.1	Classic Bluetooth and Dual-Mode BLE v4.2	None
Type	SiP Package	M.2 2230-E Module with USB and SDIO variants	Complete System on Module w/ Linux OS and 500MHz ARM A5 processor	SiP Package or Surface Mount Module	SiP Package or Surface Mount Module	SiP Package
Size (mm)	14 x 13	30 x 22	30 x 30	10 x 10 (chip) 15.5 x 21 (module)	10 x 10 x 1.6 (chip) 21 x 15.5 x 2.3 (module)	10.5 x 10.5
Transmit Power	Wi-Fi: 10 to 18 dBm BT/BLE: 7 to 10 dBm	Wi-Fi: 10 to 18 dBm BT/BLE: 7 to 10 dBm	Wi-Fi: 10 to 18 dBm BT/BLE: 7 to 10 dBm	Wi-Fi: 12.5 to 17.5 dBm BT/BLE: 4 to 8.5 dBm	Wi-Fi: 11 to 16 dBm BT/BLE: 6 to 8 dBm	15 to 19 dBm
Receiver Sensitivity	Wi-Fi: -55 to -95 dBm BT/BLE: -88 to -95 dBm	Wi-Fi: -55 to -95 dBm BT/BLE: -88 to -95 dBm	Wi-Fi: -55 to -95 dBm BT/BLE: -88 to -95 dBm	Wi-Fi: -72 to -88 dBm BT/BLE: -87 to -94 dBm	Wi-Fi: -71 to -87 dBm BT/BLE: -84.5 to -92 dBm	-71 to -90 dBm
Temperature Range	-30°C to 85°C (-22°F to 185°F)	-30°C to 85°C (-22°F to 185°F)	-30°C to 85°C (-22°F to 185°F)	-40°C to 85°C (-40°F to 185°F)	-40°C to 85°C (-40°F to 185°F)	-40°C to 85°C (-40°F to 185°F)
Operating Systems	Android, Linux	Android, Linux	Onboard Linux OS and MCU supports any connectable device	Linux	Linux and Android	Standalone onboard ARMC CM3 or external host
Security	WEP, WPA, WPA2	WEP, WPA, WPA2	WEP, WPA, WPA2	WEP, WPA, WPA2	WEP, WPA/WPA2 Personal, WMM	WEP, WPA/WPA2 Personal
Encryption	WEP, TKIP, AES (full EAP type and certificate support)	WEP, TKIP, AES (full EAP type and certificate support)	WEP, TKIP, AES (full EAP type and certificate support)	TKIP, AES	AES, TKIP, CKIP	AES, TKIP
Certifications	FCC, IC, ETSI	FCC, IC, ETSI	FCC, IC, ETSI	FCC, IC, ETSI, Giteki, RCM	FCC, IC, ETSI	FCC, IC, ETSI
Management	Laird Connection Manager (LCM) and Software Developer's Kit	Laird Connection Manager (LCM) and Software Developer's Kit	Command Line & browser-accessible Laird Connection Manager	Linux driver support, and Sterling- LWB for WICED reference platform	Direct driver support for Linux and SIG-certified Bluetooth driver	Pre-integrated TiWiConnect Cloud agent

Modules not shown at actual size.

To learn more, visit connectivity.lairdtech.com/wi-fi
or contact us at CS-Sales@lairdtech.com